

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"20040240865"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 15:50
L3	63	228/33.ccls.	US-PGPUB	OR	ON	2008/02/15 15:55
L4	62	228/256.ccls.	US-PGPUB	OR	ON	2008/02/15 15:56
L5	100	228/245.ccls.	US-PGPUB	OR	ON	2008/02/15 15:58
L6	30	228/42.ccls.	US-PGPUB	OR	ON	2008/02/15 15:59
L7	5	228/261.ccls.	US-PGPUB	OR	ON	2008/02/15 16:00
L8	38	392/407.ccls.	US-PGPUB	OR	ON	2008/02/15 16:00
L9	84	392/418.ccls.	US-PGPUB	OR	ON	2008/02/15 16:01
L10	5	((solder\$3 or bump\$3) same ((halogen adj lamp) or radiat\$3) same ((form\$3 or flush\$3) same gas)).clm.	US-PGPUB	OR	ON	2008/02/15 16:04

L11	2	((solder\$3 or bump\$3 or braz\$3) same (clamp\$3 or jig or fasten\$3 or hold\$3 or grip\$4) same ((chip or wafer or ball or electrode or wire) with (mount\$3 or head)) same ((form\$3 or flush\$3) same gas)).clm.	US-PGPUB	OR	ON	2008/02/15 16:22
L12	1	((solder\$3 or bump\$3 or braz\$3) same (clamp\$3 or jig or fasten\$3 or hold\$3 or grip\$4) same ((chip or wafer or ball or electrode or wire) with (mount\$3 or head)) same ((form\$3 or flush\$3) same (window or plate or channel or cover or shield\$3) same gas)).clm.	US-PGPUB	OR	ON	2008/02/15 16:24
L13	1	((solder\$3 or bump\$3 or braz\$3) same (clamp\$3 or jig or fasten\$3 or hold\$3 or grip\$4) same ((chip or wafer or ball or electrode or wire) with (mount\$3 or head)) same (gas same (channel or port or passage or outlet or inlet or opening or exit) same (channel or window or shield\$3 or cover or plate))).clm.	US-PGPUB	OR	ON	2008/02/15 16:26
L16	40	((solder\$3 or bump\$3) with ((halogen adj lamp) or radiat\$3) with ((form\$3 or flush\$3) with gas))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:29

L17	801	((solder\$3 or bump\$3 or braz\$3) same (clamp\$3 or jig or fasten\$3 or hold\$3 or grip\$4) same ((chip or wafer or ball or electrode or wire) with (mount\$3 or head)) same ((form\$3 or flush\$3) same gas))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:30
L18	500	((solder\$3 or bump\$3 or braz\$3) same (clamp\$3 or jig or fasten\$3 or hold\$3 or grip\$4) same ((chip or wafer or ball or electrode or wire) with (mount\$3 or head)) same ((form\$3 or flush\$3) same (window or plate or channel or cover or shield\$3) same gas))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:31
L19	396	((solder\$3 or bump\$3 or braz\$3) same (clamp\$3 or jig or fasten\$3 or hold\$3 or grip\$4) same ((chip or wafer or ball or electrode or wire) with (mount\$3 or head)) same (gas same (channel or port or passage or outlet or inlet or opening or exit) same (channel or window or shield\$3 or cover or plate)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:32
L21	2002	("228/42,33,245,256,261").ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:33

L22	1245	(392/407,418).ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:34
L23	3247	21 or 22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:34
L24	6	23 and 17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:34
L25	4	23 and 18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:35
L26	4	23 and 19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:35

2/15/2008 4:37:45 PM

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